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## (54) BASE FOR PLANOGRAPHIC PRINTING PLATE

(57) Abstract:

PURPOSE: To simplify a graining process, by a method wherein a surface of an Al plate is provided with oblong form press-recessed parts in a density not lower than a specified value so that the recessed parts partially overlap with each other to form a wavy pattern, and specified minute recessed parts are provided thereon by electrochemical etching. CONSTITUTION: The surface of the Al plate is provided with the oblong form press-recessed parts in a density of not lower than 200 pieces/mm2 so that the recessed parts overlap with each other to form a wavy pattern, and then the minute recessed parts with an average pitch of 1W10μm are provided thereon by electrochemical etching. Roughening of the surface of the Al plate is conducted by, e.g., a pressure roll the surface of which is previously roughened, whereby the surface of the Al plate is provided with the oblong press-recessed parts in a high density so that fringe parts partially overlap with each other to form a wavy pattern. The shape and the density of the oblong recesed parts are associated with adaptability for a planographic printing plate, and they are adjusted to within respective predetermined ranges. The density of the oblong press-recessed parts is preferably not lower than 200 pieces/mm2, desirably, 1,000W10,000 pieces/mm2.

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